

NEW/FEATURED PRODUCTS

Introduction/
Plg. Solutions/
Brush Contact

LRM (Line Replaceable Modules)
Options/
Accessories

Ruggedized
VME64x/
VITA 60, 66

High Density
HSB3
Hi Speed

Low Mating Force MIL-DTL-55302
Docking Conn./
Accessories/Install.

Rack & Panel
Brush
Ruggedized

LMD/LMS
Rectangular
Interconnects

Other
Rectangular
Interconnects

Amphenol has become the leader in interconnection products through its long history of engineering expertise for product solution solving.

New and innovative solutions are under development every day within our highly skilled engineering departments who are teamed with marketing product managers and production specialists. They are always striving to meet new customer requirements in ever changing markets.

The teams have a customer-driven approach to produce the end result: quality interconnect products that meet or exceed customer demands.

Below are some of the newer product solutions that have been developed in response to our customers' ever evolving requirements for board level and rectangular interconnects.

New/Featured Product

HDB³/HSB³ High Density and High Speed Brush Connector Series

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Tighter .070 inch X .060 inch staggered grid spacing provides higher density in a compact-height board level connector.

Solution:
Higher contact density plus lower mated height - thus maximizing board space.



New/Featured Product

High Speed GigaStak[™], Gigastak-LG[™], DigiStak[™] and DigiStak-X[™] LRM Connectors

Pages 31-36

High speed inserts provide data transference of up to 6.25 Gb/s.



Solution:
Hi Speed performance in a ruggedized connector. Utilizes new cStack[™] termination - solderless interconnection between flex and board.



New/Featured Product

LRM Connectors with High Power RADSOK[®] Contacts

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High Amperage RADSOK[®] socket contacts are designed into LRM connectors for higher power applications. The RADSOK[®] socket imparts high current flow across the connection with minimal voltage loss with its hyperbolic, stamped grid configuration.

Solution:
High Amperage RADSOK[®] socket contacts allow for passing of larger amounts of current with lower mating forces than standard contacts.



New/Featured Product

VITA-66.1 Fiber Optic Interconnects

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A reliable high speed connection for the most extreme commercial and military environments. This ruggedized interconnect is among the highest density of connector products on the market.

Solution:
Higher Density in a rectangular board level connector package.



New/Featured Product

VIPER[®] High-Speed Interconnects

Pages 45 & 46

A shielded, high density, hi-speed modular interconnect with press-fit termination. VITA 46, VITA 48 and VITA 60 foot-print compatibility. Designed for 10 + Gb/s data rate performance.



Solution:
To meet and exceed the requirements for today's high performance, high speed applications.



For assistance with your specific interconnection requirements, give a call to the Amphenol sales representative in your area, (go online to amphenol-aerospace.com) or call for product assistance at Amphenol Aerospace, 800-678-0141 or 607-563-5011.